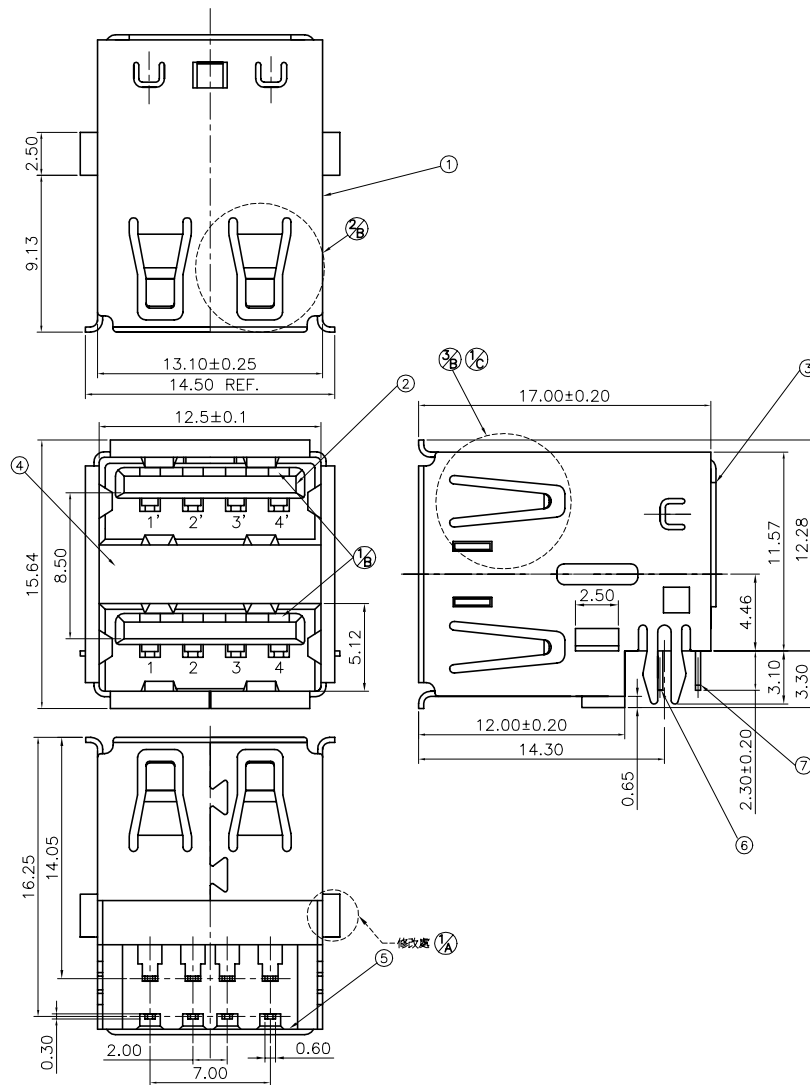
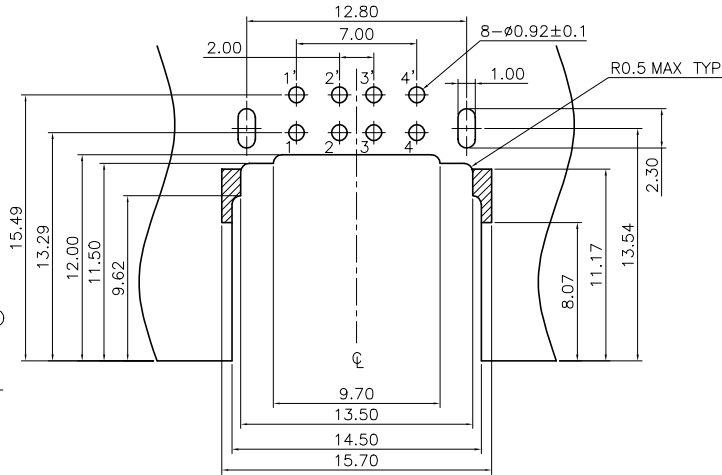




Recommended P.C.B Layout



NOTE:
020122MR008 22ZA

1. Selective plating
"S1,-05u" Min. gold in contact area/
100u" Min. Tin in solder area.
"S2,-Gold flash in contact area/
100u" Min. Tin in solder area.
"S3,-10u" Min. gold in contact area/
100u" Min. Tin in solder area.
"S4,-15u" Min. gold in contact area/
100u" Min. Tin in solder area.
"S5,-30u" Min. gold in contact area/
100u" Min. Tin in solder area.
"S6,-50u" Min. gold in contact area/
100u" Min. Tin in solder area.

7	TERMINAL-2	Phos.Bronze		GOLD/TIN
6	TERMINAL-1	Phos.Bronze		GOLD/TIN
5	BACK-COVER	L.C.P	BLACK	UL 94V-0
4	SHELL-MID	C 2680 H		NICK PLATED
3	SHELL-BACK	C 2680 H		NICK PLATED
2	HOUSING	L.C.P	BLACK	UL 94V-0
1	SHELL	C 2680 H		NICK PLATED
NO. DESCRIPTION		MATERIAL	COLOR	REMARK

SUYIN
CONNECTOR

CUSTOMER COPY	TITLE: USB Series A Type Dual Port Dip Type			
PART NO.	020122MR008SX22ZA			
PART NO. (OLD)	2522AY-08GXT-V			
DRAWING NO.	D	020122MR008SX22ZA		
SCALE	4:1	UNIT	mm	A4

ECN (DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED
EC1T-021114-07	C	02/11/14	C1:修改鐵殼彈片	宋勃逸	宋權哲	Angle ±2°
EC1T-020805-06	B	02/08/05	B1:增加偷料孔;B2,B3:修改鐵殼彈片	宋勃逸	宋權哲	30 ~ ±0.50
	A	02/08/05	A1:修改鐵殼PAD	宋勃逸	宋權哲	10 ~ 30 ±0.30
	O	02/07/08	NEW			~ 10 ±0.15

DRAW	張建邦	02/06/28
DESIGN	張建邦	02/06/28
CHECK	宋權哲	02/07/02
APPRO.	宋權哲	02/07/02